

Application No. 09/814,057

**III. AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A semiconductor device comprising:  
a semiconductor chip;  
a wiring board joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip, the wiring board having a wiring board thickness; and

a warp preventing board joined to the other surface of the semiconductor chip and composed of the same material as that of the wiring board, the warp preventing board having a warp preventing board thickness substantially equal to the wiring board thickness, wherein an external connection member for surface mounting is arranged on a surface, facing away from the semiconductor chip, of the wiring board, wherein

the warp preventing board is another wiring board.

another semiconductor chip electrically connected to the warp preventing board being joined to a surface facing away from the semiconductor chip, of the warp preventing board.

2. - 3. (Canceled)

4. (Original) The semiconductor device according to claim 1, wherein a wiring material for electrically connecting the wiring board and the warp preventing board is interposed therebetween.

5. (Previously Presented) A semiconductor device comprising:  
a semiconductor chip;  
a wiring board joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip; and  
a warp preventing board joined to the other surface of the semiconductor chip and composed of the same material as that of the wiring board, wherein the warp preventing board is another wiring board,

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another semiconductor chip electrically connected to the warp preventing board being joined to a surface, facing away from the semiconductor chip, of the warp preventing board.

6. (New) The semiconductor device according to claim 5, wherein a wiring material for electrically connecting the wiring board and the warp preventing board is interposed therebetween.

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